



PATENT APPLICATION

IN THE U.S. PATENT AND TRADEMARK OFFICE

June 25, 2010

Applicants: Katsuyuki TSUCHIDA et al

For: COPPER ELECTROLYTIC SOLUTION CONTAINING AS ADDITIVE  
COMPOUND HAVING SPECIFIC SKELETON, AND  
ELECTROLYTIC COPPER FOIL MANUFACTURED THEREWITH

Serial No.: 10/588 686

Group: 1795

Confirmation No.: 9917

Filed: August 7, 2006

Examiner: Wong

International Application No.: PCT/JP2005/022662

International Filing Date: December 9, 2005

Atty. Docket No.: 4700.P0335US

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**RESPONSE**

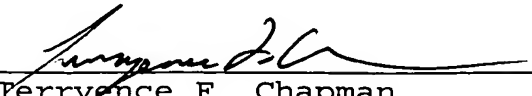
Sir:

In response to the Office Action dated April 7, 2010,  
please amend the above-identified application as follows:

(Please see following pages.)

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**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being  
deposited with the United States Postal Service with  
sufficient postage as first class mail in an envelope  
addressed to: Commissioner for Patents, P.O. Box 1450,  
Alexandria, VA 22313-1450, on June 25, 2010.

  
Terryence F. Chapman